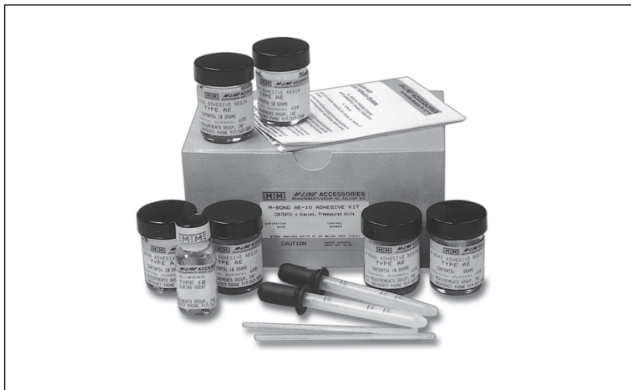


Strain Gage Adhesive



OTHER ACCESSORIES USED IN AN M-BOND AE-10 INSTALLATION:

- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- PCT-2A Cellophane Tape
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION

Two-component, 100%-solids epoxy system for general-purpose stress analysis. Transparent, medium viscosity. Cure time as low as six hours at +75°F [+24°C] may be used. Elevated-temperature postcure is recommended for

maximum stability, and/or tests above room temperature. Highly resistant to moisture and most chemicals, particularly when postcured. For maximum elongation, bonding surface must be roughened. Cryogenic applications require very thin gluelines.

CHARACTERISTICS

Operating Temperature Range:

Long Term: -320° to +200°F [-195° to +95°C].

Elongation Capabilities:

1% at -320°F [-195°C];
6% to 10% at +75°F [+24°C];
15% at +200°F [+95°C].

Shelf Life:

12 months at +75°F [+24°C]; 18 months at +20°F [-7°C]. If crystals form in resin jar, heat to +120°F [+50°C] for 30 minutes. Cool before mixing.

Pot Life:

15 to 20 minutes at +75°F [+24°C]. Can be extended by cooling jar or by spreading adhesive on clean aluminum plate.

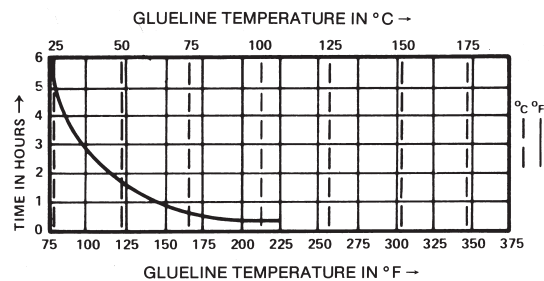
Clamping Pressure:

5 to 20 psi [35 to 140 kN/m²].

Cure Requirements:

Preferred Room-Temperature Cure: 24-48 hours at +75°F [+24°C].

Recommended Postcure: 2 hours at 25°F [15°C] above maximum operating temperature.



PACKAGING

Kit:

6 mixing jars [10 g ea] Resin
1 bottle [15 ml] Curing Agent 10
6 calibrated pipettes
6 stirring rods

Bulk:

200 g Resin
40 g Curing Agent 10
3 calibrated pipettes

References:

Instruction Bulletin B-137, "Strain Gage Applications with M-Bond AE-10, AE-15, and GA-2 Adhesive Systems", included in each kit.